



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#11/b/c  
4/1/3  
Surber

Applicant: Kouichi Tanigawa

Atty. Docket No. 075834.00104

Serial No.: 09/ 934,154

Group Art Unit: 2823

Filed: August 21, 2001

Examiner: William D. Coleman

Invention: "SOLID-STATE IMAGING DEVICE"

DRAWING AMENDMENT

Assistant Commissioner of Patents  
Washington, D.C. 20231

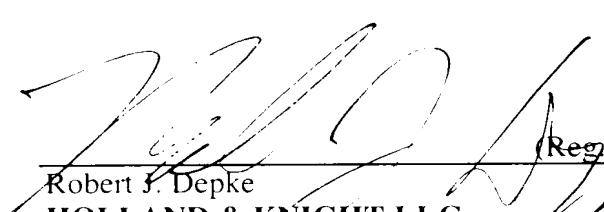
ATTN: Official Draftsman

SIR:

Applicant has attached a copy of Applicant's proposed changes to Figures 6-11<sup>th</sup> of the referenced application. The proposed changes are indicated in red ink. Applicant respectfully requests that the changes be accepted and entered in this application. Applicant states that formal drawings with the proposed changes set forth therein will be submitted upon receiving a Notice of Allowance for this application.

Respectfully submitted,

Date: March 17, 2003

  
Robert J. Depke

(Reg #37,607)

**HOLLAND & KNIGHT LLC**

131 South Dearborn Street, 30<sup>th</sup> Floor  
Chicago, Illinois 60603

Tel: (312) 422-9050

Attorney for Applicant



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Ex  
#128  
4/11/3  
Suler

Applicant: Kouichi Tanigawa

Atty. Docket No. 075834.00104

Serial No.: 09/ 934,154

Group Art Unit: 2823

Filed: August 21, 2001

Examiner: William D. Coleman

Invention: "SOLID-STATE IMAGING DEVICE"

AMENDMENT A

Commissioner for Patents  
Washington, D.C. 20231

SIR:

PETITION FOR EXTENSION OF TIME

Applicant hereby petitions for a three month extension of time to respond to the outstanding Office Action under 37 C.F.R. §1.136(a). The time to respond is thus extended to March 18, 2003. Applicant has included a check in the amount of \$930.00 as payment of the required fee set forth in 37 C.F.R. §1.17(a).

In response to the Office Action dated September 18, 2002, please amend the application as follows:

IN THE CLAIMS:

1. (Currently Amended) An improved process for producing a solid-state imaging device comprising the steps of: forming a light-receiving portion of a pixel in a region [on the] of a substrate [surface], forming a convex lens with an upwardly curved surface which is embedded in an inter-layer dielectric above said light-receiving portion, and forming an on-chip lens above said convex lens, wherein said improvement comprises forming sequentially said light-receiving portion, forming an inter-layer dielectric having a depression in its surface above said light-